



Material Declaration Sheet

Vishay General Semiconductor - VGSC

Date 20/Aug/21

Part / Product Family Details

Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemption used
P6SMBnn(A)-M3 SMB10Jxx(A)-M3 SM6TnnA-M3 SMBGxx(A)-M3 SMBJxx(A)-M3 P6SMBnnC(A)-M3 SMZG3nnnA-M3 SMZJ3nnnA-M3 SM6TnnCA-M3 SMB8JxxC(A)-M3 SMBGxxC(A)-M3 SMBJxxC(A)-M3 SMBZ59nnB-M3 SMZG3nnnB-M3 SMZJ3nnnB-M3	YES WITH EXEMPTION	01-12-2004	0.093	N/A	Yes	China	Two

Material Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00260	100.00	1000000	2.80	Exemption No:7(c)-I
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.03640	100.00	1000000	39.14	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00315	92.50	925000	3.38	Exemption No:7(a)
		Tin	7440-31-5	0.00017	5.00	50000	0.18	
		Silver	7440-22-4	0.00008	2.50	25000	0.09	
Encapsulation	Other duromers	Silica	60676-86-0	0.03880	80.00	800000	41.72	
		Epoxy Resin	29690-82-2	0.00485	10.00	100000	5.22	
		Phenol Resin	9003-35-4	0.00461	9.50	95000	4.95	
		Carbon Black	1333-86-4	0.00024	0.50	5000	0.26	
Surface finish	Other special metals	Tin	7440-31-5	0.00210	100.00	1000000	2.26	

EU-RoHS Directive- 2015/863/EU MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium ,Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP)

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.
(ii) Substance weight are derived from MSDS.

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